



## Product Change Notification / RMES-05LTHK605

---

### Date:

05-Aug-2022

### Product Category:

Memory

### PCN Type:

Manufacturing Change

### Notification Subject:

eSign # E000123576: Qualification of 66.88K wafer technology for AT24C256C-XHL-B, AT24C256C-XHL-T, AT24C256C-SSHL-B, AT24C256C-SSHL-T, AT24C256C-MAHL-T and AT24C256C-MAHL-E catalog part numbers (CPN) available in 8L TSSOP (4.4mm), 8L SOIC (3.90mm) and 8L UDFN (2x3x0.6mm) packages at UMC Fab 8D fabrication site.

### Affected CPNs:

[RMES-05LTHK605\\_Affected\\_CPN\\_08052022.pdf](#)

[RMES-05LTHK605\\_Affected\\_CPN\\_08052022.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of 66.88K wafer technology for AT24C256C-XHL-B, AT24C256C-XHL-T, AT24C256C-SSHL-B, AT24C256C-SSHL-T, AT24C256C-MAHL-T and AT24C256C-MAHL-E catalog part numbers (CPN) available in 8L TSSOP (4.4mm), 8L SOIC (3.90mm) and 8L UDFN (2x3x0.6mm) packages at UMC Fab 8D fabrication site.

### Pre and Post Change Summary:

	Pre Change	Post Change	
Wafer Technology	35.8k wafer technology	35.8k wafer technology	66.88K wafer technology
Fabrication Location	Microchip Fabrication Site FAB 5 (Colorado Springs, CO USA)	Microchip Fabrication Site FAB 5 (Colorado Springs, CO USA)	UMC Fab 8D (Hsin-Chu, Taiwan)
Wafer Diameter	6 inches (150 mm)	6 inches (150 mm)	8 inches (200 mm)
Quality certification	ISO/TS16949	ISO/TS16949	ISO/TS16949

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying 66.88K wafer technology at UMC Fab 8D fabrication site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**

September 19, 2022 (date code: 2239)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2022					September 2022			
Workweek	3 2	3 3	3 4	3 5	3 6	37	38	39	40
Qual Report Availability	x								
Final PCN Issue Date	x								
Estimated Implementation Date								x	

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**August 05, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_RMES-05LTHK605\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

---

RMES-05LTHK605 - eSign # E000123576: Qualification of 66.88K wafer technology for AT24C256C-XHL-B, AT24C256C-XHL-T, AT24C256C-SSHL-B, AT24C256C-SSHL-T, AT24C256C-MAHL-T and AT24C256C-MAHL-E catalog part numbers (CPN) available in 8L TSSOP (4.4mm), 8L SOIC (3.90mm) and 8L UDFN (2x3x0.6mm) packages at UMC Fab 8D fabrication site.

---

Affected Catalog Part Numbers (CPN)

AT24C256C-XHL-B

AT24C256C-XHL-T

AT24C256C-SSHL-B

AT24C256C-SSHL-T

AT24C256C-MAHL-T

AT24C256C-MAHL-E